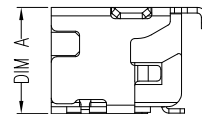
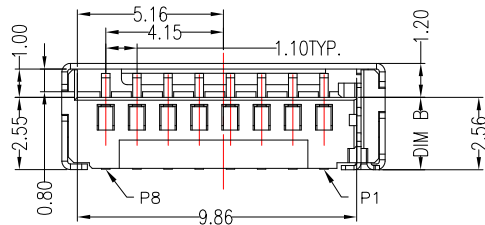


PCB LAYOUT

DIM A	DIM B
2.65	1.45
3.00	1.86



**SPECIFICATION**

Electrical :

- 1.Contact Resistance: 50 mΩ Max.
- 2.Insulation Resistance: 1000 MΩ Min.
- 3.Dielectric Withstanding Voltage: 500V RMS.
- 4.Life Cycles: 1500 cycles Min
- 5.Mate Force: 4.5kgf Max
- 6.Unmate Force: 0.5kgf Min

Material:

- 1.Housing: LCP,Black
- 2.Contact: Copper Alloy
- 3.Shell: SPCC

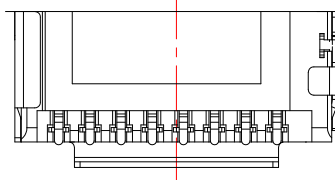
Finish:

- 1.Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

Environmental:

- 1.Operating Temperature: -25°C ~ +85°C.

Pin No.	NAME
1	DAT2
2	CD/DAT3
3	CMD
4	VDD
5	CLK
6	VSS
7	DAT0
8	DAT1



**RoHS Compliant**

TOLERANCES ARE

**MORETHANALL**  
PCB CONNECTORS  
Cable ASSEMBLIES

DRAWING BY CY

CHECKED BY GENIUS

UNIT / mm

SCALE 1 : 1

DATE

SIZE A4

PJECTION

Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3°

照片框

**ORDER INFORMATION**

TFC-WXBE10Hxx-08-LF  
SERIES | | | LEADFREE  
| | | 08 WAY  
| | | H26:HIGH 2.65mm  
| | | H30:HIGH 3.00mm  
90°SMT  
NON PUSH | EAR 1.0mm  
BOTTOM CONTACT

**煜倫股份有限公司**

www.morethanall.com

DESCRIPTION: MICRO SD 卡 短體不帶偵測PIN